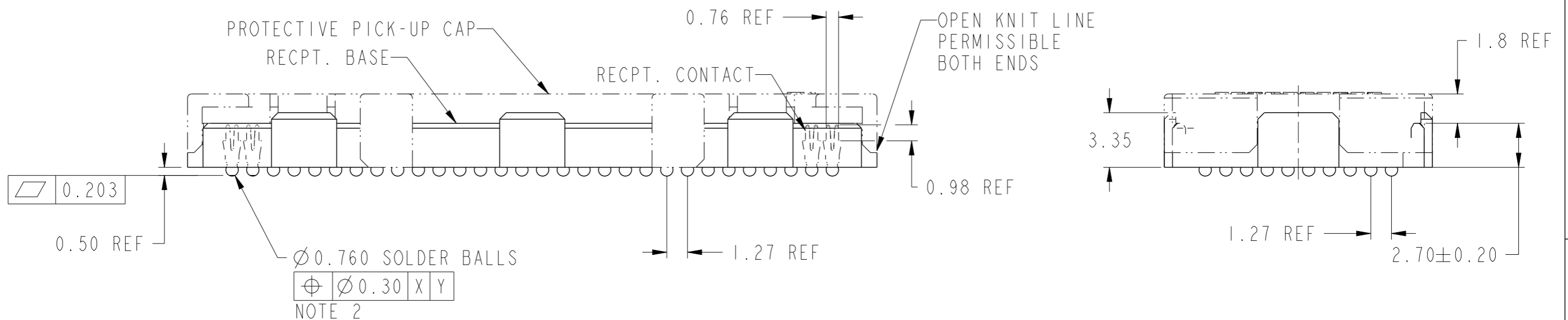
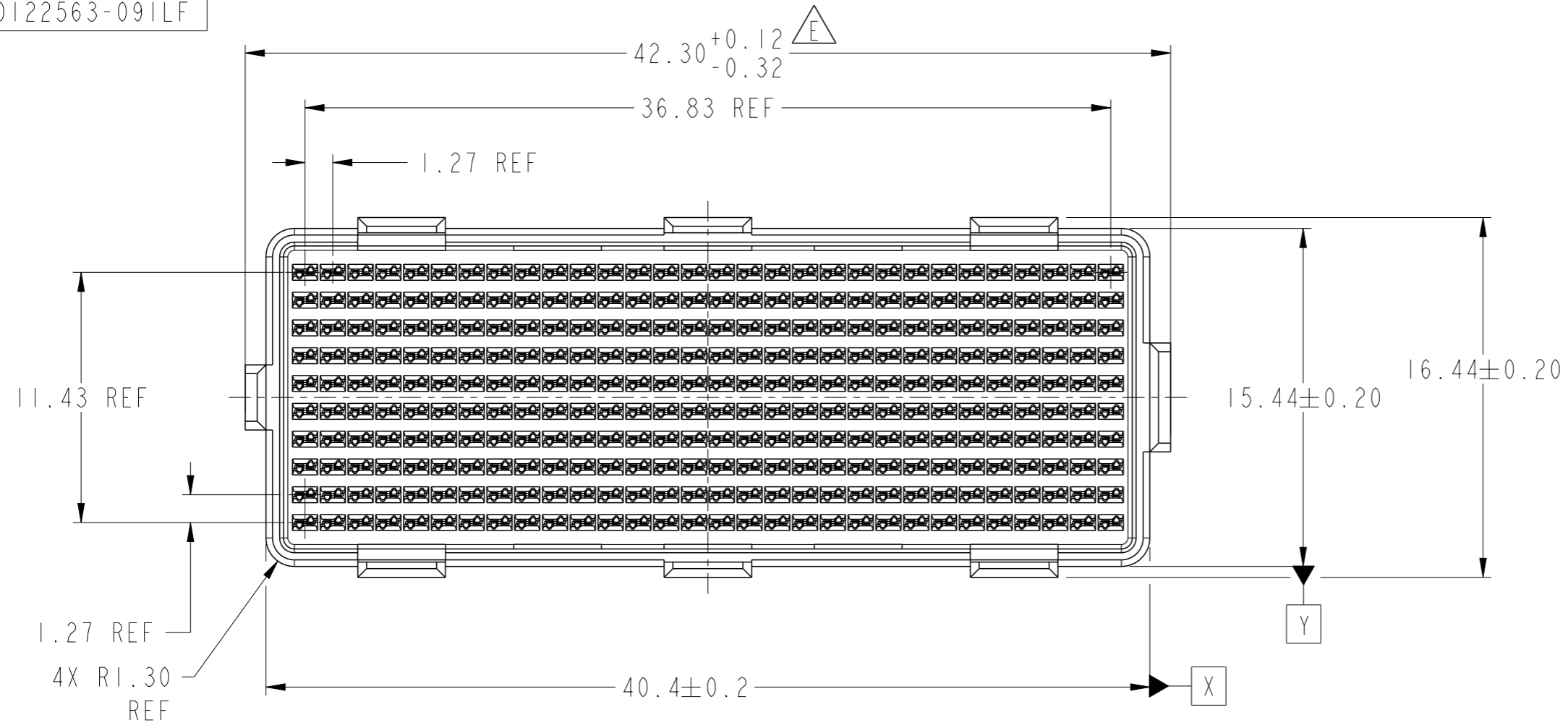


PRODUCT NUMBER
10122563-091LF



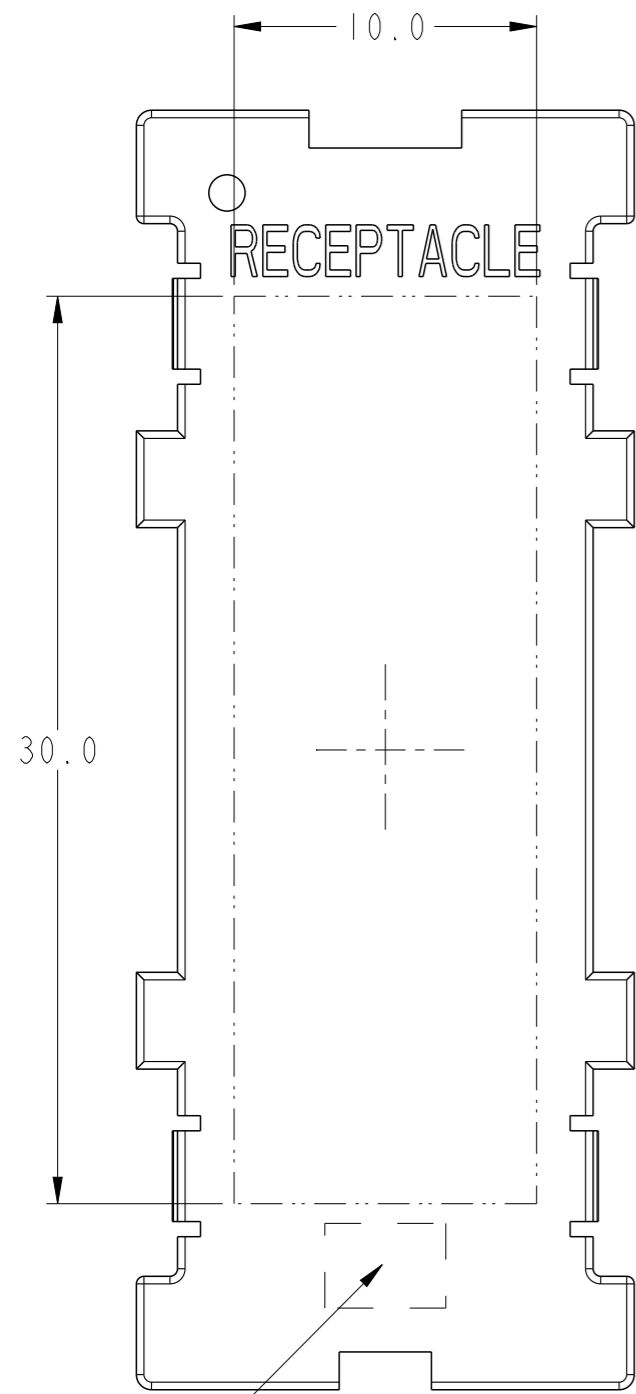
0.203

Ø0.760 SOLDER BALLS

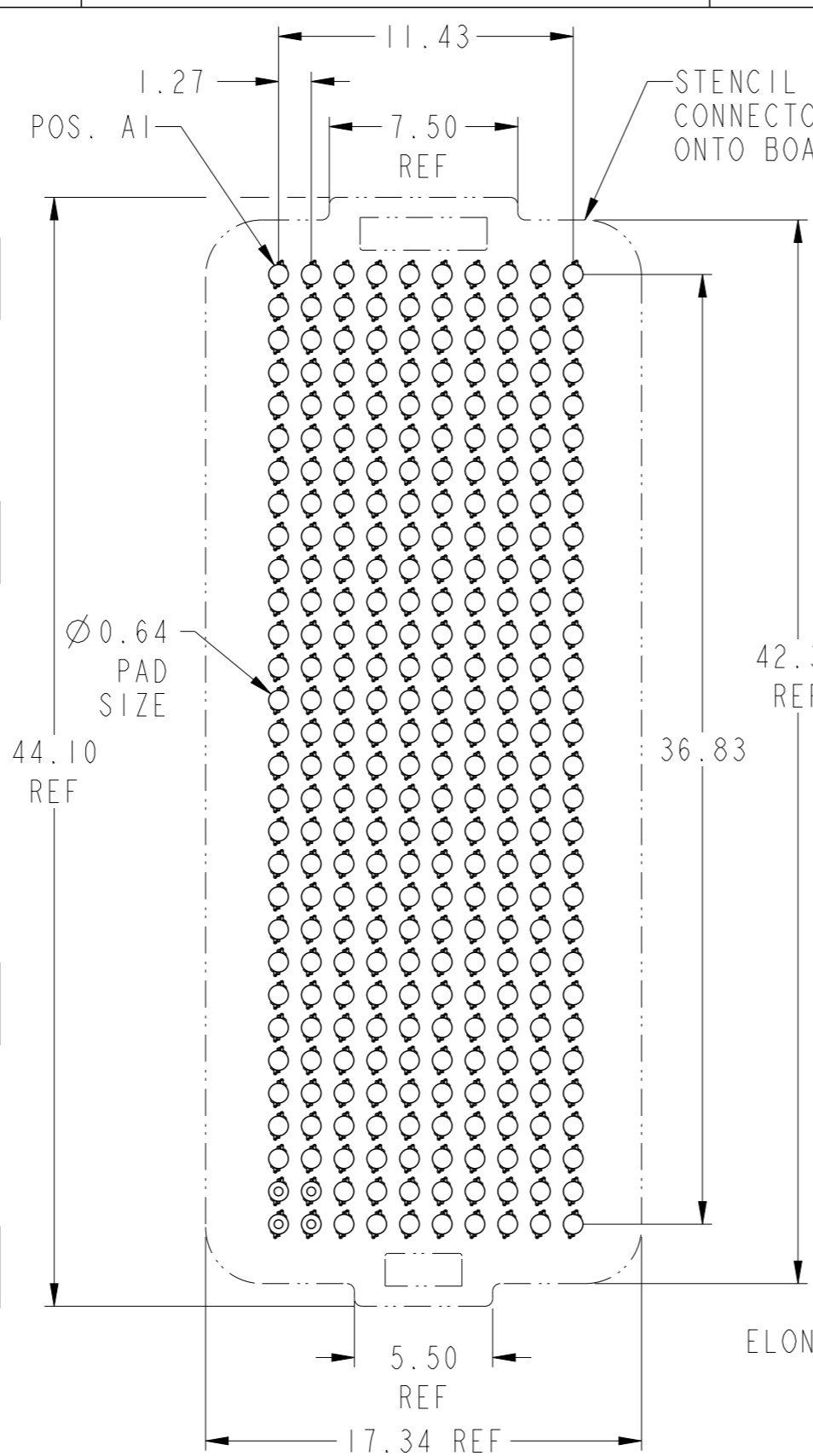
⊕ Ø0.30 X Y
NOTE 2

spec ref	-	dr	S Jaganathan	2012/08/31	projection	mm	size	A3	scale	1:1			
tolerance std	ASME Y14.5	eng	Dave Horchler	2013/10/23			ecn no	ELX-V-16129-1					
TOLERANCES UNLESS OTHERWISE SPECIFIED		chr	-	apppr			R Marshall	2013/10/23	product family	MEG-ARRAY	rel level	Released	
surface	3.2	linear	0.X	±0.3		4mm RECEPTACLE ASSEMBLY (BLACK) 10 X 30 = 300 POS.	dwg no 10122563	rev F	ASME Y14.5		angular	0°	±2°
		linear	0.XX	±0.10					www.fci.com	cat. no.	-	Product - Customer Drw	sheet 1 of 3
		linear	0.XXX	±0.050									

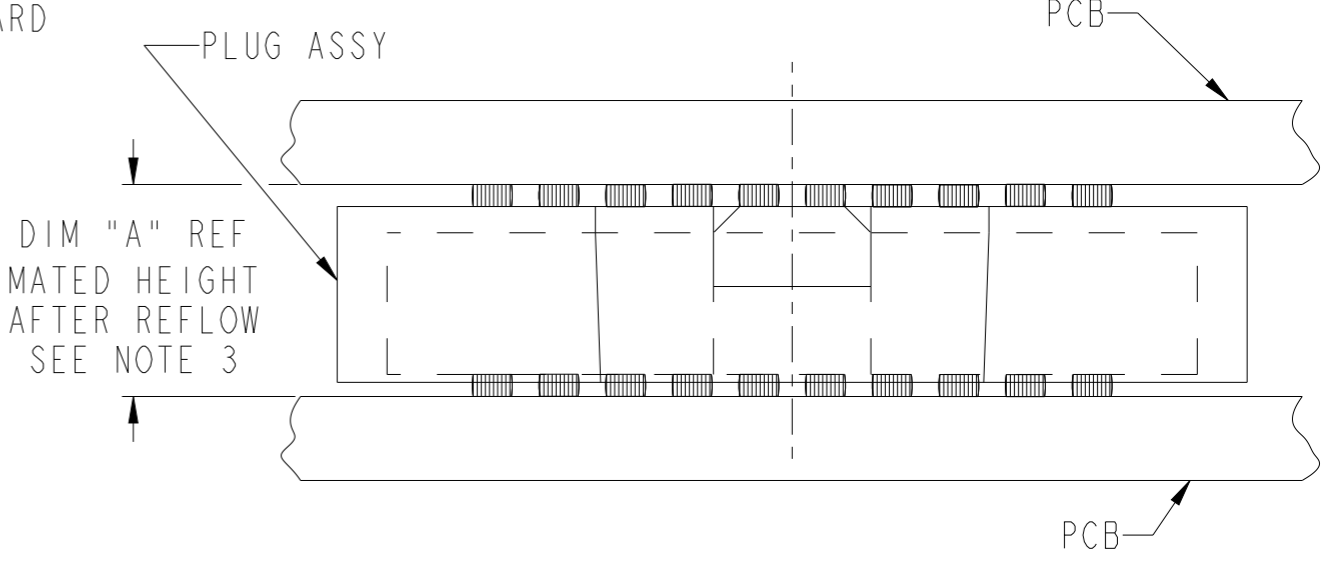
PRODUCT NUMBER
10122563-091LF



NOTE 8
FLAT AREA FOR PICK-UP CAP

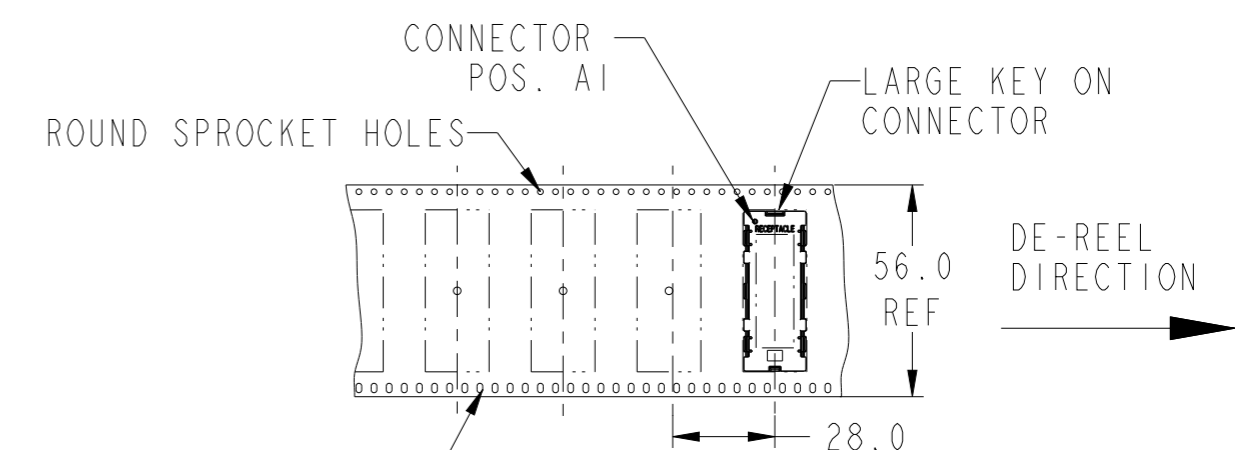


BOARD PATTERN



MATED HEIGHT AFTER REFLOW IS BASED ON \varnothing 0.64mm PAD (METAL-DEFINED) AND 0.13mm SOLDER PASTE STENCIL THICKNESS. SEE NOTE 3

END VIEW - MATED CONNECTORS
SCALE NONE



TAPE & REEL PACKAGING
PER EIA 481-3
SCALE NONE

spec ref	-	dr	S Jaganathan	2012/08/31	projection	mm	size	A3	scale	1:1				
tolerance std	ASME Y14.5	eng	Dave Horchler	2013/10/23			ecn no	ELX-V-16129-1						
TOLERANCES UNLESS OTHERWISE SPECIFIED		chr	-	apppr				R Marshall	2013/10/23	product family	MEG-ARRAY	rel level	Released	
surface	3.2	linear	0.X	± 0.3		4mm RECEPTACLE ASSEMBLY (BLACK) 10 X 30 = 300 POS.	dwg no 10122563	rev F	ASME Y14.5		angular	0°	$\pm 2^\circ$	
			0.XX	± 0.10					cat. no.	-	Product - Customer Drw	sheet 2 of 3		
			0.XXX	± 0.050										

PRODUCT NUMBER
10122563-091LF

NOTES:

1. MATERIAL:
HOUSING: LCP-BLACK
CONTACT: COPPER ALLOY

PLATING:
CONTACT: 15 μ " (0.38 μ m) GXT OVER Ni UNDERPLATE
(GOLD SUBSTITUTION PERMISSABLE)
SOLDER BALL: LEAD FREE 95.5Sn/4Ag/0.5Cu
2. SOLDER BALLS WILL NOT HAVE PERFECT SPHERICAL SHAPES DUE TO REFLOW ATTACHMENT.
3. MATED HEIGHT WHEN MATED WITH 10122562-002LF WILL BE APPROXIMATELY 4mm. MATED HEIGHT WILL BE EFFECTED BY CUSTOMER'S PCB DESIGN AND REFLOW PROCESS.
4. FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION.
5. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-47-0004 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION.
6. CURRENT COMPANY LOGO TO BE VISIBLE IN APPROXIMATE AREA SHOWN.

spec ref -		dr	S Jaganathan	2012/08/31	projection	mm	size	A3	scale	1:1	
tolerance std	ASME Y14.5	TOLERANCES UNLESS OTHERWISE SPECIFIED			eng	Dave Horchler	2013/10/23	ecn no ELX-V-16129-1			
surface	3.2	linear	0.X	± 0.3	chr	-	product family		MEG-ARRAY	rel level	Released
			0.XX	± 0.10	appr	R Marshall	2013/10/23	4mm RECEPTACLE ASSEMBLY (BLACK)		dwg no	10122563
			0.XXX	± 0.050	www.fci.com		cat. no.	-	Product - Customer Drw	rev	F
		angular	0°	$\pm 2^\circ$					sheet 3 of 3		



Copyright FCI.